

**CHUCK ASSEMBLY OF ETCHING APPARATUS FOR
PREVENTING BYPRODUCTS**

ABSTRACT OF THE DISCLOSURE

5 A chuck assembly of an etching apparatus capable of improving an etching rate at an edge portion of a wafer, thereby preventing byproducts from being formed along the edge portion of the wafer is disclosed. The chuck assembly comprises a chuck body comprising a stepped portion at an edge side portion of the chuck body for supporting a central portion of a wafer; an edge ring, received in the stepped portion of the chuck body, for supporting an edge portion of the wafer, wherein the edge ring has less resistance than the resistance of the wafer; and an insulating ring provided at a surrounding portion of the chuck body, for supporting a bottom portion of the edge ring, the bottom portion of the edge ring being extended toward outside of the chuck body.

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